

Title (en)  
RAW MATERIAL FOR FORMING THIN FILM, METHOD FOR PRODUCING THIN FILM, AND SCANDIUM COMPOUND

Title (de)  
ROHMATERIAL ZUR FORMUNG EINER DÜNNSCHICHT, VERFAHREN ZUR HERSTELLUNG EINER DÜNNSCHICHT UND SCANDIUMVERBINDUNG

Title (fr)  
MATIÈRE PREMIÈRE PERMETTANT LA FORMATION D'UN FILM MINCE, PROCÉDÉ DE PRODUCTION D'UN FILM MINCE ET COMPOSÉ DE SCANDIUM

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Application  
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Abstract (en)  
The present invention provides a thin-film forming raw material including a scandium compound represented by the following general formula (1), a method of producing a thin-film including using the thin-film forming raw material, and a novel scandium compound:where  $R^{1}$  represents an alkyl group having 1 to 4 carbon atoms,  $R^{2}$  represents an alkyl group having 2 or 3 carbon atoms, and  $R^{3}$  represents a hydrogen atom or an alkyl group having 1 to 4 carbon atoms.

IPC 8 full level  
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